

PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT3308878

SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
CONVEYING PARTY DATA		
	Name	Execution Date
	SHUNPEI YAMAZAKI	08/23/2011
RECEIVING PARTY DATA		
Name:	SEMICONDUCTOR ENERGY LABORATORY CO., LTD.	
Street Address:	398, HASE	
City:	ATSUGI-SHI, KANAGAWA-KEN	
State/Country:	JAPAN	
Postal Code:	243-0036	
PROPERTY NUMBERS Total: 1		
Property Type	Number	
Application Number:	14658876	
CORRESPONDENCE DATA		
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<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>		
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ATTORNEY DOCKET NUMBER:	12732-0934003	
NAME OF SUBMITTER:	JANELLE A. JACKSON	
SIGNATURE:	/Janelle A. Jackson/	
DATE SIGNED:	04/14/2015	
Total Attachments: 1		
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ASSIGNMENT

For valuable consideration, I, Shunpei YAMAZAKI of Setagaya, Tokyo, Japan hereby assign to Semiconductor Energy Laboratory Co., Ltd., a Japanese corporation having a place of business at:

398, Hase, Atsugi-shi, Kanagawa-ken, 243-0036 Japan

and its successors and assigns (collectively hereinafter called "the Assignee"), the entire right, title and interest throughout the world in the inventions and improvements which are subject of an application for United States Patent signed by me this day, entitled SPUTTERING TARGET AND METHOD FOR MANUFACTURING SEMICONDUCTOR DEVICE, filed August 30, 2011, and assigned U.S. Serial Number 13/221,252, and I authorize and request the Assignee or the attorneys appointed in said application to hereafter complete this assignment by inserting above the filing date and serial number of said application when known; this assignment including said application, any and all United States and foreign patents, utility models, and design registrations granted for any of said inventions or improvements, and the right to claim priority based on the filing date of said application under the International Convention for the Protection of Industrial Property, the Patent Cooperation Treaty, the European Patent Convention, and all other treaties of like purposes; and I authorize the Assignee to apply in all countries in my name or in its own name for patents, utility models, design registrations and like rights of exclusion and for inventors' certificates for said inventions and improvements; and I agree for myself and my respective heirs, legal representatives and assigns, without further compensation to perform such lawful acts and to sign such further applications, assignments, Preliminary Statements and other lawful documents as the Assignee may reasonably request to effectuate fully this assignment.

Signature



Name:

Shunpei YAMAZAKI

Date:

08/23/2011